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## Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

## **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

### **Details**

Product Status	Active
Number of LABs/CLBs	80
Number of Logic Elements/Cells	640
Total RAM Bits	-
Number of I/O	113
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	144-LQFP
Supplier Device Package	144-TQFP (20x20)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo640e-4tn144c">https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo640e-4tn144c</a>

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## Features

- **Non-volatile, Infinitely Reconfigurable**
  - Instant-on – powers up in microseconds
  - Single chip, no external configuration memory required
  - Excellent design security, no bit stream to intercept
  - Reconfigure SRAM based logic in milliseconds
  - SRAM and non-volatile memory programmable through JTAG port
  - Supports background programming of non-volatile memory
- **Sleep Mode**
  - Allows up to 100x static current reduction
- **TransFR™ Reconfiguration (TFR)**
  - In-field logic update while system operates
- **High I/O to Logic Density**
  - 256 to 2280 LUT4s
  - 73 to 271 I/Os with extensive package options
  - Density migration supported
  - Lead free/RoHS compliant packaging
- **Embedded and Distributed Memory**
  - Up to 27.6 Kbits sysMEM™ Embedded Block RAM
  - Up to 7.7 Kbits distributed RAM
  - Dedicated FIFO control logic

**Table 1-1. MachXO Family Selection Guide**

Device	LCMXO256	LCMXO640	LCMXO1200	LCMXO2280
LUTs	256	640	1200	2280
Dist. RAM (Kbits)	2.0	6.1	6.4	7.7
EBR SRAM (Kbits)	0	0	9.2	27.6
Number of EBR SRAM Blocks (9 Kbits)	0	0	1	3
V <sub>CC</sub> Voltage	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V
Number of PLLs	0	0	1	2
Max. I/O	78	159	211	271
<b>Packages</b>				
100-pin TQFP (14x14 mm)	78	74	73	73
144-pin TQFP (20x20 mm)		113	113	113
100-ball csBGA (8x8 mm)	78	74		
132-ball csBGA (8x8 mm)		101	101	101
256-ball caBGA (14x14 mm)		159	211	211
256-ball ftBGA (17x17 mm)		159	211	211
324-ball ftBGA (19x19 mm)				271

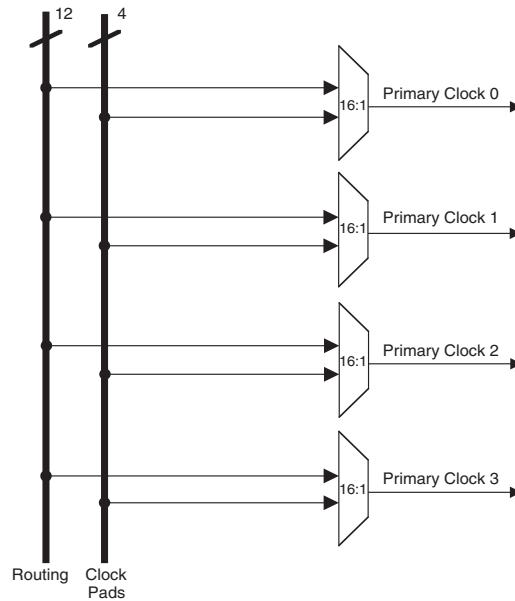
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The ispLEVER design tool takes the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

## Clock/Control Distribution Network

The MachXO family of devices provides global signals that are available to all PFUs. These signals consist of four primary clocks and four secondary clocks. Primary clock signals are generated from four 16:1 muxes as shown in Figure 2-7 and Figure 2-8. The available clock sources for the MachXO256 and MachXO640 devices are four dual function clock pins and 12 internal routing signals. The available clock sources for the MachXO1200 and MachXO2280 devices are four dual function clock pins, up to nine internal routing signals and up to six PLL outputs.

**Figure 2-7. Primary Clocks for MachXO256 and MachXO640 Devices**



## sysCLOCK Phase Locked Loops (PLLs)

The MachXO1200 and MachXO2280 provide PLL support. The source of the PLL input divider can come from an external pin or from internal routing. There are four sources of feedback signals to the feedback divider: from CLKINTFB (internal feedback port), from the global clock nets, from the output of the post scalar divider, and from the routing (or from an external pin). There is a PLL\_LOCK signal to indicate that the PLL has locked on to the input clock signal. Figure 2-10 shows the sysCLOCK PLL diagram.

The setup and hold times of the device can be improved by programming a delay in the feedback or input path of the PLL which will advance or delay the output clock with reference to the input clock. This delay can be either programmed during configuration or can be adjusted dynamically. In dynamic mode, the PLL may lose lock after adjustment and not relock until the  $t_{LOCK}$  parameter has been satisfied. Additionally, the phase and duty cycle block allows the user to adjust the phase and duty cycle of the CLKOS output.

The sysCLOCK PLLs provide the ability to synthesize clock frequencies. Each PLL has four dividers associated with it: input clock divider, feedback divider, post scalar divider, and secondary clock divider. The input clock divider is used to divide the input clock signal, while the feedback divider is used to multiply the input clock signal. The post scalar divider allows the VCO to operate at higher frequencies than the clock output, thereby increasing the frequency range. The secondary divider is used to derive lower frequency outputs.

**Figure 2-10. PLL Diagram**

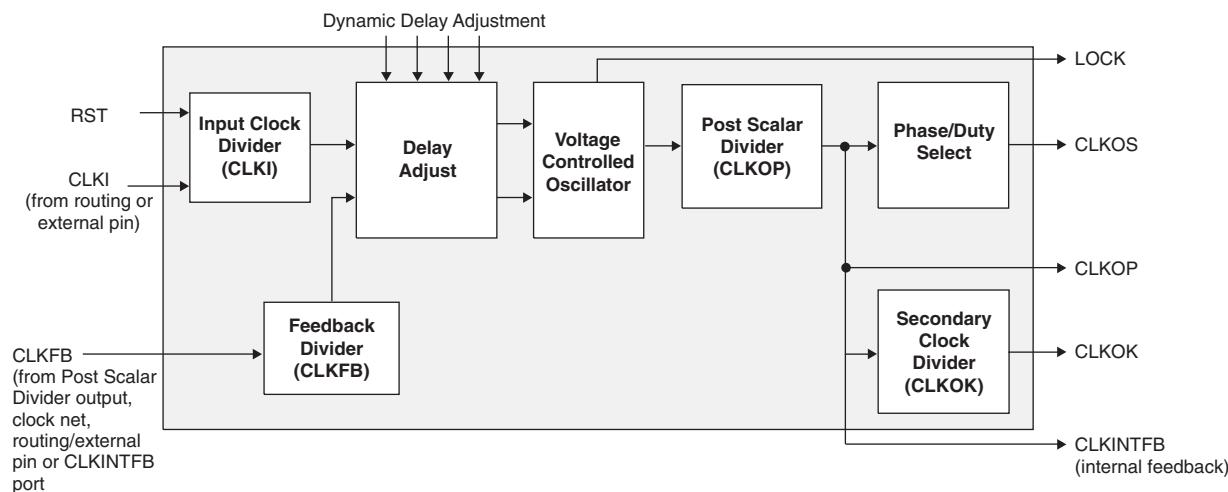
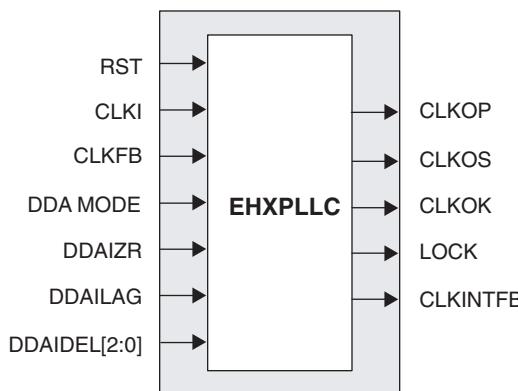


Figure 2-11 shows the available macros for the PLL. Table 2-5 provides signal description of the PLL Block.

**Figure 2-11. PLL Primitive**



The EBR memory supports three forms of write behavior for single or dual port operation:

1. **Normal** – data on the output appears only during the read cycle. During a write cycle, the data (at the current address) does not appear on the output. This mode is supported for all data widths.
2. **Write Through** – a copy of the input data appears at the output of the same port. This mode is supported for all data widths.
3. **Read-Before-Write** – when new data is being written, the old contents of the address appears at the output. This mode is supported for x9, x18 and x36 data widths.

#### FIFO Configuration

The FIFO has a write port with Data-in, CEW, WE and CLKW signals. There is a separate read port with Data-out, RCE, RE and CLKR signals. The FIFO internally generates Almost Full, Full, Almost Empty and Empty Flags. The Full and Almost Full flags are registered with CLKW. The Empty and Almost Empty flags are registered with CLKR. The range of programming values for these flags are in Table 2-7.

**Table 2-7. Programmable FIFO Flag Ranges**

Flag Name	Programming Range
Full (FF)	1 to (up to $2^N-1$ )
Almost Full (AF)	1 to Full-1
Almost Empty (AE)	1 to Full-1
Empty (EF)	0

N = Address bit width

The FIFO state machine supports two types of reset signals: RSTA and RSTB. The RSTA signal is a global reset that clears the contents of the FIFO by resetting the read/write pointer and puts the FIFO flags in their initial reset state. The RSTB signal is used to reset the read pointer. The purpose of this reset is to retransmit the data that is in the FIFO. In these applications it is important to keep careful track of when a packet is written into or read from the FIFO.

#### Memory Core Reset

The memory array in the EBR utilizes latches at the A and B output ports. These latches can be reset asynchronously. RSTA and RSTB are local signals, which reset the output latches associated with Port A and Port B respectively. The Global Reset (GSRN) signal resets both ports. The output data latches and associated resets for both ports are as shown in Figure 2-13.



# MachXO Family Data Sheet

## DC and Switching Characteristics

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### Absolute Maximum Ratings<sup>1, 2, 3</sup>

	LCMXO E (1.2V)	LCMXO C (1.8V/2.5V/3.3V)
Supply Voltage V <sub>CC</sub> .....	-0.5 to 1.32V .....	-0.5 to 3.75V .....
Supply Voltage V <sub>CCAUX</sub> .....	-0.5 to 3.75V .....	-0.5 to 3.75V .....
Output Supply Voltage V <sub>CCIO</sub> .....	-0.5 to 3.75V .....	-0.5 to 3.75V .....
I/O Tristate Voltage Applied <sup>4</sup> .....	-0.5 to 3.75V .....	-0.5 to 3.75V .....
Dedicated Input Voltage Applied <sup>4</sup> .....	-0.5 to 3.75V .....	-0.5 to 4.25V .....
Storage Temperature (ambient).....	-65 to 150°C .....	-65 to 150°C .....
Junction Temp. (T <sub>j</sub> ) .....	+125°C .....	+125°C .....

1. Stress above those listed under the "Absolute Maximum Ratings" may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.
2. Compliance with the Lattice *Thermal Management* document is required.
3. All voltages referenced to GND.
4. Overshoot and undershoot of -2V to (V<sub>IHMAX</sub> + 2) volts is permitted for a duration of <20ns.

### Recommended Operating Conditions<sup>1</sup>

Symbol	Parameter	Min.	Max.	Units
V <sub>CC</sub>	Core Supply Voltage for 1.2V Devices	1.14	1.26	V
	Core Supply Voltage for 1.8V/2.5V/3.3V Devices	1.71	3.465	V
V <sub>CCAUX</sub> <sup>3</sup>	Auxiliary Supply Voltage	3.135	3.465	V
V <sub>CCIO</sub> <sup>2</sup>	I/O Driver Supply Voltage	1.14	3.465	V
t <sub>TJCOM</sub>	Junction Temperature Commercial Operation	0	+85	°C
t <sub>TJIND</sub>	Junction Temperature Industrial Operation	-40	100	°C
t <sub>TFLASHCOM</sub>	Junction Temperature, Flash Programming, Commercial	0	+85	°C
t <sub>TFLASHIND</sub>	Junction Temperature, Flash Programming, Industrial	-40	100	°C

1. Like power supplies must be tied together. For example, if V<sub>CCIO</sub> and V<sub>CC</sub> are both 2.5V, they must also be the same supply. 3.3V V<sub>CCIO</sub> and 1.2V V<sub>CCIO</sub> should be tied to V<sub>CCAUX</sub> or 1.2V V<sub>CC</sub> respectively.
2. See recommended voltages by I/O standard in subsequent table.
3. V<sub>CC</sub> must reach minimum V<sub>CC</sub> value before V<sub>CCAUX</sub> reaches 2.5V.

### MachXO Programming/Erase Specifications

Symbol	Parameter	Min.	Max.	Units
N <sub>PROGCYC</sub>	Flash Programming Cycles per t <sub>RETENTION</sub>		1,000	Cycles
	Flash Functional Programming Cycles		10,000	Cycles
t <sub>RETENTION</sub>	Data Retention at 125° Junction Temperature	10		Years

## sysIO Differential Electrical Characteristics

### LVDS

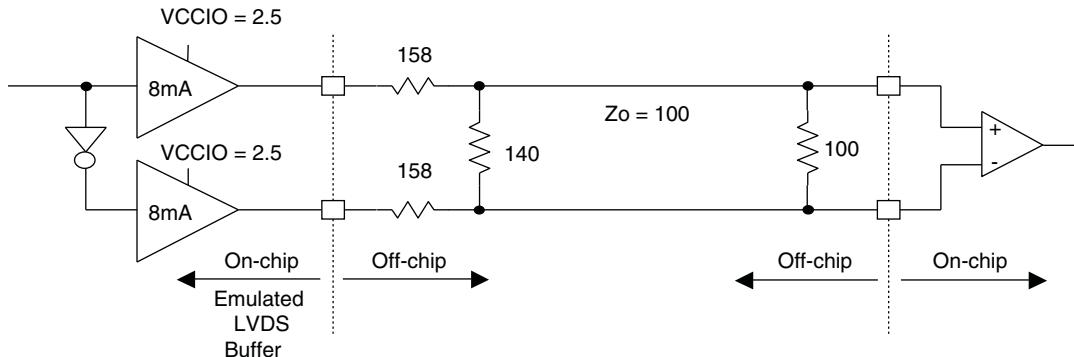
#### Over Recommended Operating Conditions

Parameter Symbol	Parameter Description	Test Conditions	Min.	Typ.	Max.	Units
$V_{INP}, V_{INM}$	Input Voltage		0	—	2.4	V
$V_{THD}$	Differential Input Threshold		+/-100	—	—	mV
$V_{CM}$	Input Common Mode Voltage	$100\text{mV} \leq V_{THD}$	$V_{THD}/2$	1.2	1.8	V
		$200\text{mV} \leq V_{THD}$	$V_{THD}/2$	1.2	1.9	V
		$350\text{mV} \leq V_{THD}$	$V_{THD}/2$	1.2	2.0	V
$I_{IN}$	Input current	Power on	—	—	+/-10	$\mu\text{A}$
$V_{OH}$	Output high voltage for $V_{OP}$ or $V_{OM}$	$R_T = 100 \text{ Ohm}$	—	1.38	1.60	V
$V_{OL}$	Output low voltage for $V_{OP}$ or $V_{OM}$	$R_T = 100 \text{ Ohm}$	0.9V	1.03	—	V
$V_{OD}$	Output voltage differential	$(V_{OP} - V_{OM}), R_T = 100 \text{ Ohm}$	250	350	450	mV
$\Delta V_{OD}$	Change in $V_{OD}$ between high and low		—	—	50	mV
$V_{OS}$	Output voltage offset	$(V_{OP} - V_{OM})/2, R_T = 100 \text{ Ohm}$	1.125	1.25	1.375	V
$\Delta V_{OS}$	Change in $V_{OS}$ between H and L		—	—	50	mV
$I_{OSD}$	Output short circuit current	$V_{OD} = 0\text{V}$ Driver outputs shorted	—	—	6	mA

### LVDS Emulation

MachXO devices can support LVDS outputs via emulation (LVDS25E), in addition to the LVDS support that is available on-chip on certain devices. The output is emulated using complementary LVCMS outputs in conjunction with resistors across the driver outputs on all devices. The scheme shown in Figure 3-1 is one possible solution for LVDS standard implementation. Resistor values in Figure 3-1 are industry standard values for 1% resistors.

**Figure 3-1. LVDS Using External Resistors (LVDS25E)**



Note: All resistors are  $\pm 1\%$ .

The LVDS differential input buffers are available on certain devices in the MachXO family.

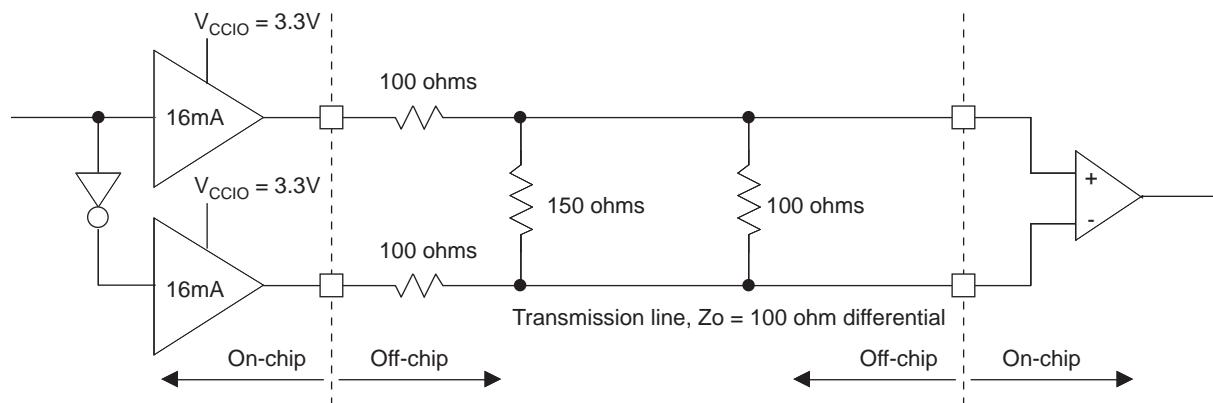
**Table 3-2. BLVDS DC Conditions<sup>1</sup>**
**Over Recommended Operating Conditions**

Symbol	Description	Nominal		Units
		Zo = 45	Zo = 90	
Z <sub>OUT</sub>	Output impedance	100	100	Ohms
R <sub>TLEFT</sub>	Left end termination	45	90	Ohms
R <sub>TRIGHT</sub>	Right end termination	45	90	Ohms
V <sub>OH</sub>	Output high voltage	1.375	1.48	V
V <sub>OL</sub>	Output low voltage	1.125	1.02	V
V <sub>OD</sub>	Output differential voltage	0.25	0.46	V
V <sub>CM</sub>	Output common mode voltage	1.25	1.25	V
I <sub>DC</sub>	DC output current	11.2	10.2	mA

1. For input buffer, see LVDS table.

## LVPECL

The MachXO family supports the differential LVPECL standard through emulation. This output standard is emulated using complementary LVCMS outputs in conjunction with a parallel resistor across the driver outputs on all the devices. The LVPECL input standard is supported by the LVDS differential input buffer on certain devices. The scheme shown in Figure 3-3 is one possible solution for point-to-point signals.

**Figure 3-3. Differential LVPECL**

**Table 3-3. LVPECL DC Conditions<sup>1</sup>**
**Over Recommended Operating Conditions**

Symbol	Description	Nominal	Units
Z <sub>OUT</sub>	Output impedance	100	Ohms
R <sub>P</sub>	Driver parallel resistor	150	Ohms
R <sub>T</sub>	Receiver termination	100	Ohms
V <sub>OH</sub>	Output high voltage	2.03	V
V <sub>OL</sub>	Output low voltage	1.27	V
V <sub>OD</sub>	Output differential voltage	0.76	V
V <sub>CM</sub>	Output common mode voltage	1.65	V
Z <sub>BACK</sub>	Back impedance	85.7	Ohms
I <sub>DC</sub>	DC output current	12.7	mA

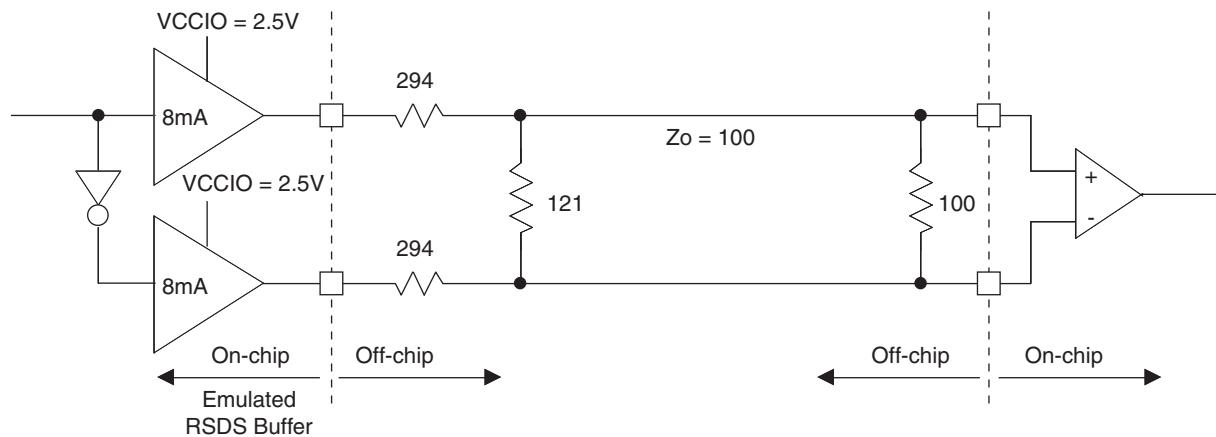
1. For input buffer, see LVDS table.

For further information on LVPECL, BLVDS and other differential interfaces please see details of additional technical documentation at the end of the data sheet.

## RSDS

The MachXO family supports the differential RSDS standard. The output standard is emulated using complementary LVCMS outputs in conjunction with a parallel resistor across the driver outputs on all the devices. The RSDS input standard is supported by the LVDS differential input buffer on certain devices. The scheme shown in Figure 3-4 is one possible solution for RSDS standard implementation. Use LVDS25E mode with suggested resistors for RSDS operation. Resistor values in Figure 3-4 are industry standard values for 1% resistors.

**Figure 3-4. RSDS (Reduced Swing Differential Standard)**



**Table 3-4. RSDS DC Conditions**

Parameter	Description	Typical	Units
$Z_{OUT}$	Output impedance	20	Ohms
$R_S$	Driver series resistor	294	Ohms
$R_P$	Driver parallel resistor	121	Ohms
$R_T$	Receiver termination	100	Ohms
$V_{OH}$	Output high voltage	1.35	V
$V_{OL}$	Output low voltage	1.15	V
$V_{OD}$	Output differential voltage	0.20	V
$V_{CM}$	Output common mode voltage	1.25	V
$Z_{BACK}$	Back impedance	101.5	Ohms
$I_{DC}$	DC output current	3.66	mA

## Typical Building Block Function Performance<sup>1</sup>

### Pin-to-Pin Performance (LVCMS25 12mA Drive)

Function	-5 Timing	Units
<b>Basic Functions</b>		
16-bit decoder	6.7	ns
4:1 MUX	4.5	ns
16:1 MUX	5.1	ns

### Register-to-Register Performance

Function	-5 Timing	Units
<b>Basic Functions</b>		
16:1 MUX	487	MHz
16-bit adder	292	MHz
16-bit counter	388	MHz
64-bit counter	200	MHz
<b>Embedded Memory Functions (1200 and 2280 Devices Only)</b>		
256x36 Single Port RAM	284	MHz
512x18 True-Dual Port RAM	284	MHz
<b>Distributed Memory Functions</b>		
16x2 Single Port RAM	434	MHz
64x2 Single Port RAM	320	MHz
128x4 Single Port RAM	261	MHz
32x2 Pseudo-Dual Port RAM	314	MHz
64x4 Pseudo-Dual Port RAM	271	MHz

1. The above timing numbers are generated using the ispLEVER design tool. Exact performance may vary with device and tool version. The tool uses internal parameters that have been characterized but are not tested on every device.

Rev. A 0.19

### Derating Logic Timing

Logic Timing provided in the following sections of the data sheet and the ispLEVER design tools are worst case numbers in the operating range. Actual delays may be much faster. The ispLEVER design tool from Lattice can provide logic timing numbers at a particular temperature and voltage.

## MachXO External Switching Characteristics<sup>1</sup>

Over Recommended Operating Conditions

Parameter	Description	Device	-5		-4		-3		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
<b>General I/O Pin Parameters (Using Global Clock without PLL)<sup>1</sup></b>									
t <sub>PD</sub>	Best Case t <sub>PD</sub> Through 1 LUT	LCMxo256	—	3.5	—	4.2	—	4.9	ns
		LCMxo640	—	3.5	—	4.2	—	4.9	ns
		LCMxo1200	—	3.6	—	4.4	—	5.1	ns
		LCMxo2280	—	3.6	—	4.4	—	5.1	ns
t <sub>CO</sub>	Best Case Clock to Output - From PFU	LCMxo256	—	4.0	—	4.8	—	5.6	ns
		LCMxo640	—	4.0	—	4.8	—	5.7	ns
		LCMxo1200	—	4.3	—	5.2	—	6.1	ns
		LCMxo2280	—	4.3	—	5.2	—	6.1	ns
t <sub>SU</sub>	Clock to Data Setup - To PFU	LCMxo256	1.3	—	1.6	—	1.8	—	ns
		LCMxo640	1.1	—	1.3	—	1.5	—	ns
		LCMxo1200	1.1	—	1.3	—	1.6	—	ns
		LCMxo2280	1.1	—	1.3	—	1.5	—	ns
t <sub>H</sub>	Clock to Data Hold - To PFU	LCMxo256	-0.3	—	-0.3	—	-0.3	—	ns
		LCMxo640	-0.1	—	-0.1	—	-0.1	—	ns
		LCMxo1200	0.0	—	0.0	—	0.0	—	ns
		LCMxo2280	-0.4	—	-0.4	—	-0.4	—	ns
f <sub>MAX_IO</sub>	Clock Frequency of I/O and PFU Register	LCMxo256	—	600	—	550	—	500	MHz
		LCMxo640	—	600	—	550	—	500	MHz
		LCMxo1200	—	600	—	550	—	500	MHz
		LCMxo2280	—	600	—	550	—	500	MHz
t <sub>SKEW_PRI</sub>	Global Clock Skew Across Device	LCMxo256	—	200	—	220	—	240	ps
		LCMxo640	—	200	—	220	—	240	ps
		LCMxo1200	—	220	—	240	—	260	ps
		LCMxo2280	—	220	—	240	—	260	ps

1. General timing numbers based on LVCMS2.5V, 12 mA.

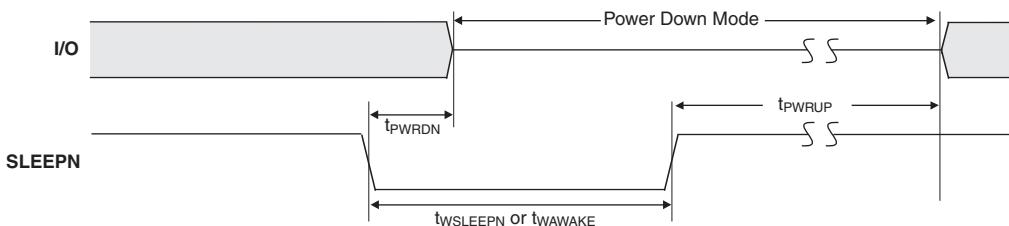
Rev. A 0.19

## MachXO "C" Sleep Mode Timing

Symbol	Parameter	Device	Min.	Typ.	Max	Units
$t_{PWRDN}$	SLEEPN Low to Power Down	All	—	—	400	ns
$t_{PWRUP}$	SLEEPN High to Power Up	LCMXO256	—	—	400	μs
		LCMXO640	—	—	600	μs
		LCMXO1200	—	—	800	μs
		LCMXO2280	—	—	1000	μs
$t_{WSLEEPN}$	SLEEPN Pulse Width	All	400	—	—	ns
$t_{WAWAKE}$	SLEEPN Pulse Rejection	All	—	—	100	ns

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## Flash Download Time



Symbol	Parameter	Min.	Typ.	Max.	Units	
$t_{REFRESH}$	Minimum $V_{CC}$ or $V_{CCAUX}$ (later of the two supplies) to Device I/O Active	LCMXO256	—	—	0.4	ms
		LCMXO640	—	—	0.6	ms
		LCMXO1200	—	—	0.8	ms
		LCMXO2280	—	—	1.0	ms

## JTAG Port Timing Specifications

Symbol	Parameter	Min.	Max.	Units
$f_{MAX}$	TCK [BSCAN] clock frequency	—	25	MHz
$t_{BTCP}$	TCK [BSCAN] clock pulse width	40	—	ns
$t_{BTCPH}$	TCK [BSCAN] clock pulse width high	20	—	ns
$t_{BTCPL}$	TCK [BSCAN] clock pulse width low	20	—	ns
$t_{BTS}$	TCK [BSCAN] setup time	8	—	ns
$t_{BTH}$	TCK [BSCAN] hold time	10	—	ns
$t_{BTRF}$	TCK [BSCAN] rise/fall time	50	—	mV/ns
$t_{BTCO}$	TAP controller falling edge of clock to output valid	—	10	ns
$t_{BTCODIS}$	TAP controller falling edge of clock to output disabled	—	10	ns
$t_{BTCOEN}$	TAP controller falling edge of clock to output enabled	—	10	ns
$t_{BTCRS}$	BSCAN test capture register setup time	8	—	ns
$t_{BTCRH}$	BSCAN test capture register hold time	25	—	ns
$t_{BUTCO}$	BSCAN test update register, falling edge of clock to output valid	—	25	ns
$t_{BTUODIS}$	BSCAN test update register, falling edge of clock to output disabled	—	25	ns
$t_{BTUPOEN}$	BSCAN test update register, falling edge of clock to output enabled	—	25	ns

Rev. A 0.19

### Signal Descriptions

Signal Name	I/O	Descriptions
<b>General Purpose</b>		
P[Edge] [Row/Column Number]_[A/B/C/D/E/F]	I/O	<p>[Edge] indicates the edge of the device on which the pad is located. Valid edge designations are L (Left), B (Bottom), R (Right), T (Top).</p> <p>[Row/Column Number] indicates the PFU row or the column of the device on which the PIO Group exists. When Edge is T (Top) or (Bottom), only need to specify Row Number. When Edge is L (Left) or R (Right), only need to specify Column Number.</p> <p>[A/B/C/D/E/F] indicates the PIO within the group to which the pad is connected.</p> <p>Some of these user programmable pins are shared with special function pins. When not used as special function pins, these pins can be programmed as I/Os for user logic.</p> <p>During configuration of the user-programmable I/Os, the user has an option to tri-state the I/Os and enable an internal pull-up resistor. This option also applies to unused pins (or those not bonded to a package pin). The default during configuration is for user-programmable I/Os to be tri-stated with an internal pull-up resistor enabled. When the device is erased, I/Os will be tri-stated with an internal pull-up resistor enabled.</p>
GSRN	I	Global RESET signal (active low). Dedicated pad, when not in use it can be used as an I/O pin.
TSALL	I	TSALL is a dedicated pad for the global output enable signal. When TSALL is high all the outputs are tristated. It is a dual function pin. When not in use, it can be used as an I/O pin.
NC	—	No connect.
GND	—	GND - Ground. Dedicated pins.
V <sub>CC</sub>	—	VCC - The power supply pins for core logic. Dedicated pins.
V <sub>CCAUX</sub>	—	VCCAUX - the Auxiliary power supply pin. This pin powers up a variety of internal circuits including all the differential and referenced input buffers. Dedicated pins.
V <sub>CCIOx</sub>	—	V <sub>CCIO</sub> - The power supply pins for I/O Bank x. Dedicated pins.
SLEEPN <sup>1</sup>	I	Sleep Mode pin - Active low sleep pin. <sup>b</sup> When this pin is held high, the device operates normally. <sup>b</sup> This pin has a weak internal pull-up, but when unused, an external pull-up to V <sub>CC</sub> is recommended. When driven low, the device moves into Sleep mode after a specified time.
<b>PLL and Clock Functions</b> (Used as user programmable I/O pins when not used for PLL or clock pins)		
[LOC][0]_PLL[T, C]_IN	—	Reference clock (PLL) input Pads: [LOC] indicates location. Valid designations are ULM (Upper PLL) and LLM (Lower PLL). T = true and C = complement.
[LOC][0]_PLL[T, C]_FB	—	Optional feedback (PLL) input Pads: [LOC] indicates location. Valid designations are ULM (Upper PLL) and LLM (Lower PLL). T = true and C = complement.
PCLK [n]_[1:0]	—	Primary Clock Pads, n per side.
<b>Test and Programming</b> (Dedicated pins)		
TMS	I	Test Mode Select input pin, used to control the 1149.1 state machine.
TCK	I	Test Clock input pin, used to clock the 1149.1 state machine.
TDI	I	Test Data input pin, used to load data into the device using an 1149.1 state machine.
TDO	O	Output pin -Test Data output pin used to shift data out of the device using 1149.1.

<sup>1</sup>. Applies to MachXO "C" devices only. NC for "E" devices.

**LCMxo256 and LCMxo640 Logic Signal Connections: 100 csBGA (Cont.)**

LCMxo256					LCMxo640				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
P13	PB5A	1			P13	PB9C	2		T
M12*	SLEEPN	-	SLEEPN		M12*	SLEEPN	-	SLEEPN	
P14	PB5C	1		T	P14	PB9D	2		C
N13	PB5D	1		C	N13	PB9F	2		
N14	PR9B	0		C	N14	PR11D	1		C
M14	PR9A	0		T	M14	PR11B	1		C
L13	PR8B	0		C	L13	PR11C	1		T
L14	PR8A	0		T	L14	PR11A	1		T
M13	PR7D	0		C	M13	PR10D	1		C
K14	PR7C	0		T	K14	PR10C	1		T
K13	PR7B	0		C	K13	PR10B	1		C
J14	PR7A	0		T	J14	PR10A	1		T
J13	PR6B	0		C	J13	PR9D	1		
H13	PR6A	0		T	H13	PR9B	1		
G14	GNDIO0	0			G14	GNDIO1	1		
G13	PR5D	0		C	G13	PR7B	1		
F14	PR5C	0		T	F14	PR6C	1		
F13	PR5B	0		C	F13	PR6B	1		
E14	PR5A	0		T	E14	PR5D	1		
E13	PR4B	0		C	E13	PR5B	1		
D14	PR4A	0		T	D14	PR4D	1		
D13	PR3D	0		C	D13	PR4B	1		
C14	PR3C	0		T	C14	PR3D	1		
C13	PR3B	0		C	C13	PR3B	1		
B14	PR3A	0		T	B14	PR2D	1		
C12	PR2B	0		C	C12	PR2B	1		
B13	GNDIO0	0			B13	GNDIO1	1		
A13	PR2A	0		T	A13	PT9F	0		C
A12	PT5C	0			A12	PT9E	0		T
B11	PT5B	0		C	B11	PT9C	0		
A11	PT5A	0		T	A11	PT9A	0		
B12	PT4F	0		C	B12	VCCIO0	0		
A10	PT4E	0		T	A10	GNDIO0	0		
B10	PT4D	0		C	B10	PT7E	0		
A9	PT4C	0		T	A9	PT7A	0		
A8	PT4B	0	PCLK0_1**	C	A8	PT6B	0	PCLK0_1**	
B8	PT4A	0	PCLK0_0**	T	B8	PT5B	0	PCLK0_0**	C
A7	PT3D	0		C	A7	PT5A	0		T
B7	VCCAUX	-			B7	VCCAUX	-		
A6	PT3C	0		T	A6	PT4F	0		
B6	VCC	-			B6	VCC	-		
A5	PT3B	0		C	A5	PT3F	0		

**LCMxo640, LCMxo1200 and LCMxo2280 Logic Signal Connections:  
 256 caBGA / 256 ftBGA (Cont.)**

LCMxo640				LCMxo1200				LCMxo2280					
Ball Number	Ball Function	Bank	Dual Function	Ball Number	Ball Function	Bank	Dual Function	Ball Number	Ball Function	Bank	Dual Function		
J4	PL8A	3	T	J4	PL13A	6	T*	J4	PL16A	6	T*		
J5	PL8B	3	C	J5	PL13B	6	C*	J5	PL16B	6	C*		
R1	PL11A	3	T	R1	PL13C	6	T	R1	PL16C	6	T		
R2	PL11B	3	C	R2	PL13D	6	C	R2	PL16D	6	C		
-	-	-	-	-	-	-	-	GND	GND	-	-		
K5	NC			K5	PL14A	6	LLM0_PLLT_FB_A	T*	K5	PL17A	6	LLM0_PLLT_FB_A	
K4	NC			K4	PL14B	6	LLM0_PLLC_FB_A	C*	K4	PL17B	6	LLM0_PLLC_FB_A	
L5	PL10C	3	T	L5	PL14C	6	T	L5	PL17C	6	T		
L4	PL10D	3	C	L4	PL14D	6	C	L4	PL17D	6	C		
M5	NC			M5	PL15A	6	LLM0_PLLT_IN_A	T*	M5	PL18A	6	LLM0_PLLT_IN_A	
M4	NC			M4	PL15B	6	LLM0_PLLC_IN_A	C*	M4	PL18B	6	LLM0_PLLC_IN_A	
N4	PL11C	3	T	N4	PL16A	6	T	N4	PL19A	6	T		
N3	PL11D	3	C	N3	PL16B	6	C	N3	PL19B	6	C		
VCCIO3	VCCIO3	3		VCCIO6	VCCIO6	6		VCCIO6	VCCIO6	6			
GND	GNDIO3	3		GND	GNDIO6	6		GND	GNDIO6	6			
GND	GNDIO2	2		GND	GNDIO5	5		GND	GNDIO5	5			
VCCIO2	VCCIO2	2		VCCIO5	VCCIO5	5		VCCIO5	VCCIO5	5			
P4	TMS	2	TMS	P4	TMS	5	TMS	P4	TMS	5	TMS		
P2	NC			P2	PB2A	5	T	P2	PB2A	5	T		
P3	NC			P3	PB2B	5	C	P3	PB2B	5	C		
N5	NC			N5	PB2C	5	T	N5	PB2C	5	T		
R3	TCK	2	TCK	R3	TCK	5	TCK	R3	TCK	5	TCK		
N6	NC			N6	PB2D	5	C	N6	PB2D	5	C		
T2	PB2A	2	T	T2	PB3A	5	T	T2	PB3A	5	T		
T3	PB2B	2	C	T3	PB3B	5	C	T3	PB3B	5	C		
R4	PB2C	2	T	R4	PB3C	5	T	R4	PB3C	5	T		
R5	PB2D	2	C	R5	PB3D	5	C	R5	PB3D	5	C		
P5	PB3A	2	T	P5	PB4A	5	T	P5	PB4A	5	T		
P6	PB3B	2	C	P6	PB4B	5	C	P6	PB4B	5	C		
T5	PB3C	2	T	T5	PB4C	5	T	T5	PB4C	5	T		
M6	TDO	2	TDO	M6	TDO	5	TDO	M6	TDO	5	TDO		
T4	PB3D	2	C	T4	PB4D	5	C	T4	PB4D	5	C		
R6	PB4A	2	T	R6	PB5A	5	T	R6	PB5A	5	T		
GND	GNDIO2	2		GND	GNDIO5	5		GND	GNDIO5	5			
VCCIO2	VCCIO2	2		VCCIO5	VCCIO5	5		VCCIO5	VCCIO5	5			
T6	PB4B	2	C	T6	PB5B	5	C	T6	PB5B	5	C		
N7	TDI	2	TDI	N7	TDI	5	TDI	N7	TDI	5	TDI		
T8	PB4C	2	T	T8	PB5C	5	T	T8	PB6A	5	T		
T7	PB4D	2	C	T7	PB5D	5	C	T7	PB6B	5	C		
M7	NC			M7	PB6A	5	T	M7	PB7C	5	T		
M8	NC			M8	PB6B	5	C	M8	PB7D	5	C		
T9	VCCAUX	-		T9	VCCAUX	-		T9	VCCAUX	-			
R7	PB4E	2	T	R7	PB6C	5	T	R7	PB8C	5	T		
R8	PB4F	2	C	R8	PB6D	5	C	R8	PB8D	5	C		
-	-			VCCIO5	VCCIO5	5		VCCIO5	VCCIO5	5			
-	-			GND	GNDIO5	5		GND	GNDIO5	5			
P7	PB5C	2	T	P7	PB6E	5	T	P7	PB9A	4	T		
P8	PB5D	2	C	P8	PB6F	5	C	P8	PB9B	4	C		
N8	PB5A	2	T	N8	PB7A	4	T	N8	PB10E	4	T		
N9	PB5B	2	PCLK2_1***	C	N9	PB7B	4	PCLK4_1***	C	N9	PB10F	4	PCLK4_1***
P10	PB7B	2	C	P10	PB7D	4	C	P10	PB10D	4	C		
P9	PB7A	2	T	P9	PB7C	4	T	P9	PB10C	4	T		
M9	PB6B	2	PCLK2_0***	C	M9	PB7F	4	PCLK4_0***	C	M9	PB10B	4	PCLK4_0***

**LCMxo640, LCMxo1200 and LCMxo2280 Logic Signal Connections:  
 256 caBGA / 256 ftBGA (Cont.)**

LCMxo640					LCMxo1200					LCMxo2280				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
J13	PR8C	1		T	J13	PR11A	3			J13	PR14A	3		T*
GND	GND	-			GND	GND	-			GND	GND	-		
K14	PR8B	1		C	K14	PR10D	3			K14	PR13D	3		C
J14	PR8A	1		T	J14	PR10C	3			J14	PR13C	3		T
K15	PR7D	1		C	K15	PR10B	3			K15	PR13B	3		C*
J15	PR7C	1		T	J15	PR10A	3			J15	PR13A	3		T*
-	-				GND	GNDIO3	3			GND	GNDIO3	3		
-	-				VCCIO3	VCCIO3	3			VCCIO3	VCCIO3	3		
K12	NC				K12	PR9D	3			K12	PR11D	3		C
J12	NC				J12	PR9C	3			J12	PR11C	3		T
J16	PR7B	1		C	J16	PR9B	3			J16	PR11B	3		C*
H16	PR7A	1		T	H16	PR9A	3			H16	PR11A	3		T*
H15	PR6B	1		C	H15	PR8D	2			H15	PR10D	2		C
G15	PR6A	1		T	G15	PR8C	2			G15	PR10C	2		T
H14	PR5D	1		C	H14	PR8B	2			H14	PR10B	2		C*
G14	PR5C	1		T	G14	PR8A	2			G14	PR10A	2		T*
GND	GNDIO1	1			GND	GNDIO2	2			GND	GNDIO2	2		
VCCIO1	VCCIO1	1			VCCIO2	VCCIO2	2			VCCIO2	VCCIO2	2		
H13	PR6D	1		C	H13	PR7D	2			H13	PR9D	2		C
H12	PR6C	1		T	H12	PR7C	2			H12	PR9C	2		T
G13	PR4D	1		C	G13	PR7B	2			G13	PR9B	2		C*
G12	PR4C	1		T	G12	PR7A	2			G12	PR9A	2		T*
G16	PR5B	1		C	G16	PR6D	2			G16	PR7D	2		C
F16	PR5A	1		T	F16	PR6C	2			F16	PR7C	2		T
F15	PR4B	1		C	F15	PR6B	2			F15	PR7B	2		C*
E15	PR4A	1		T	E15	PR6A	2			E15	PR7A	2		T*
E16	PR3B	1		C	E16	PR5D	2			E16	PR6D	2		C
D16	PR3A	1		T	D16	PR5C	2			D16	PR6C	2		T
VCCIO1	VCCIO1	1			VCCIO2	VCCIO2	2			VCCIO2	VCCIO2	2		
GND	GNDIO1	1			GND	GNDIO2	2			GND	GNDIO2	2		
D15	PR2D	1		C	D15	PR5B	2			D15	PR6B	2		C*
C15	PR2C	1		T	C15	PR5A	2			C15	PR6A	2		T*
C16	PR2B	1		C	C16	PR4D	2			C16	PR5D	2		C
B16	PR2A	1		T	B16	PR4C	2			B16	PR5C	2		T
F14	PR3D	1		C	F14	PR4B	2			F14	PR5B	2		C*
E14	PR3C	1		T	E14	PR4A	2			E14	PR5A	2		T*
-	-	-			-	-	-			GND	GND	-		
F12	NC				F12	PR3D	2			F12	PR4D	2		C
F13	NC				F13	PR3C	2			F13	PR4C	2		T
E12	NC				E12	PR3B	2			E12	PR4B	2		C*
E13	NC				E13	PR3A	2			E13	PR4A	2		T*
D13	NC				D13	PR2B	2			D13	PR3B	2		C*
D14	NC				D14	PR2A	2			D14	PR3A	2		T*
VCCIO0	VCCIO0	0			VCCIO2	VCCIO2	2			VCCIO2	VCCIO2	2		
GND	GNDIO0	0			GND	GNDIO2	2			GND	GNDIO2	2		
GND	GNDIO0	0			GND	GNDIO1	1			GND	GNDIO1	1		
VCCIO0	VCCIO0	0			VCCIO1	VCCIO1	1			VCCIO1	VCCIO1	1		
B15	NC				B15	PT11D	1			B15	PT16D	1		C
A15	NC				A15	PT11C	1			A15	PT16C	1		T
C14	NC				C14	PT11B	1			C14	PT16B	1		C
B14	NC				B14	PT11A	1			B14	PT16A	1		T
C13	PT9F	0		C	C13	PT10F	1			C13	PT15D	1		C
B13	PT9E	0		T	B13	PT10E	1			B13	PT15C	1		T

**LCMxo640, LCMxo1200 and LCMxo2280 Logic Signal Connections:  
 256 caBGA / 256 ftBGA (Cont.)**

LCMxo640					LCMxo1200				LCMxo2280					
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
E11	NC				E11	PT10D	1		C	E11	PT15B	1		C
E10	NC				E10	PT10C	1		T	E10	PT15A	1		T
D12	PT9D	0		C	D12	PT10B	1		C	D12	PT14D	1		C
D11	PT9C	0		T	D11	PT10A	1		T	D11	PT14C	1		T
A14	PT7F	0		C	A14	PT9F	1		C	A14	PT14B	1		C
A13	PT7E	0		T	A13	PT9E	1		T	A13	PT14A	1		T
C12	PT8B	0		C	C12	PT9D	1		C	C12	PT13D	1		C
C11	PT8A	0		T	C11	PT9C	1		T	C11	PT13C	1		T
-	-			VCCIO1	VCCIO1	VCCIO1	1			VCCIO1	VCCIO1	1		
-	-			GND	GNDIO1	GNDIO1	1			GND	GNDIO1	1		
B12	PT7B	0		C	B12	PT9B	1		C	B12	PT12D	1		C
B11	PT7A	0		T	B11	PT9A	1		T	B11	PT12C	1		T
A12	PT7D	0		C	A12	PT8F	1		C	A12	PT12B	1		C
A11	PT7C	0		T	A11	PT8E	1		T	A11	PT12A	1		T
GND	GND	-		GND	GND	GND	-			GND	GND	-		
B10	PT5D	0		C	B10	PT8D	1		C	B10	PT11B	1		C
B9	PT5C	0		T	B9	PT8C	1		T	B9	PT11A	1		T
D10	PT8D	0		C	D10	PT8B	1		C	D10	PT10F	1		C
D9	PT8C	0		T	D9	PT8A	1		T	D9	PT10E	1		T
-	-			VCCIO1	VCCIO1	VCCIO1	1			VCCIO1	VCCIO1	1		
-	-			GND	GNDIO1	GNDIO1	1			GND	GNDIO1	1		
C10	PT6D	0		C	C10	PT7F	1		C	C10	PT10D	1		C
C9	PT6C	0		T	C9	PT7E	1		T	C9	PT10C	1		T
A9	PT6B	0	PCLK0_1***	C	A9	PT7D	1	PCLK1_1***	C	A9	PT10B	1	PCLK1_1***	C
A10	PT6A	0		T	A10	PT7C	1		T	A10	PT10A	1		T
E9	PT9B	0		C	E9	PT7B	1		C	E9	PT9D	1		C
E8	PT9A	0		T	E8	PT7A	1		T	E8	PT9C	1		T
D7	PT5B	0	PCLK0_0***	C	D7	PT6F	0	PCLK1_0***	C	D7	PT9B	1	PCLK1_0***	C
D8	PT5A	0		T	D8	PT6E	0		T	D8	PT9A	1		T
VCCIO0	VCCIO0	0		VCCIO0	VCCIO0	VCCIO0	0			VCCIO0	VCCIO0	0		
GND	GNDIO0	0		GND	GNDIO0	GNDIO0	0			GND	GNDIO0	0		
C8	PT4F	0		C	C8	PT6D	0		C	C8	PT8D	0		C
B8	PT4E	0		T	B8	PT6C	0		T	B8	PT8C	0		T
A8	VCCAUX	-		A8	VCCAUX	VCCAUX	-			A8	VCCAUX	-		
A7	PT4D	0		C	A7	PT6B	0		C	A7	PT7D	0		C
A6	PT4C	0		T	A6	PT6A	0		T	A6	PT7C	0		T
VCC	VCC	-		VCC	VCC	VCC	-			VCC	VCC	-		
B7	PT4B	0		C	B7	PT5F	0		C	B7	PT7B	0		C
B6	PT4A	0		T	B6	PT5E	0		T	B6	PT7A	0		T
C6	PT3C	0		T	C6	PT5C	0		T	C6	PT6A	0		T
C7	PT3D	0		C	C7	PT5D	0		C	C7	PT6B	0		C
A5	PT3E	0		T	A5	PT5A	0		T	A5	PT6C	0		T
A4	PT3F	0		C	A4	PT5B	0		C	A4	PT6D	0		C
E7	NC			E7	PT4C	0		T	E7	PT6E	0		T	
E6	NC			E6	PT4D	0		C	E6	PT6F	0		C	
B5	PT3B	0		C	B5	PT3F	0		C	B5	PT5D	0		C
B4	PT3A	0		T	B4	PT3E	0		T	B4	PT5C	0		T
D5	PT2D	0		C	D5	PT3D	0		C	D5	PT5B	0		C
D6	PT2C	0		T	D6	PT3C	0		T	D6	PT5A	0		T
C4	PT2E	0		T	C4	PT4A	0		T	C4	PT4A	0		T
C5	PT2F	0		C	C5	PT4B	0		C	C5	PT4B	0		C
-	-	-		-	-	-	-			GND	GND	-		
D4	NC			D4	PT2D	0		C	D4	PT3D	0		C	

**LCMxo2280 Logic Signal Connections: 324 ftBGA (Cont.)**

LCMxo2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
G2	PL11A	6		T*
H2	PL11B	6		C*
L3	PL11C	6		T
L5	PL11D	6		C
H1	PL12A	6		T*
VCCIO6	VCCIO6	6		
GND	GNDIO6	6		
J2	PL12B	6		C*
L4	PL12C	6		T
L6	PL12D	6		C
K2	PL13A	6		T*
K1	PL13B	6		C*
J1	PL13C	6		T
VCC	VCC	-		
L2	PL13D	6		C
M5	PL14D	6		C
M3	PL14C	6	TSALL	T
L1	PL14B	6		C*
M2	PL14A	6		T*
M1	PL15A	6		T*
N1	PL15B	6		C*
M6	PL15C	6		T
M4	PL15D	6		C
VCCIO6	VCCIO6	6		
GND	GNDIO6	6		
P1	PL16A	6		T*
P2	PL16B	6		C*
N3	PL16C	6		T
N4	PL16D	6		C
GND	GND	-		
T1	PL17A	6	LLM0_PLLT_FB_A	T*
R1	PL17B	6	LLM0_PLLC_FB_A	C*
P3	PL17C	6		T
N5	PL17D	6		C
R3	PL18A	6	LLM0_PLLT_IN_A	T*
R2	PL18B	6	LLM0_PLLC_IN_A	C*
P4	PL19A	6		T
N6	PL19B	6		C
U1	PL20A	6		T
VCCIO6	VCCIO6	6		
GND	GNDIO6	6		
GND	GNDIO5	5		
VCCIO5	VCCIO5	5		

**LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)**

LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
F16	GND	-		
H10	GND	-		
H11	GND	-		
H8	GND	-		
H9	GND	-		
J10	GND	-		
J11	GND	-		
J4	GND	-		
J8	GND	-		
J9	GND	-		
K10	GND	-		
K11	GND	-		
K17	GND	-		
K8	GND	-		
K9	GND	-		
L10	GND	-		
L11	GND	-		
L8	GND	-		
L9	GND	-		
N2	GND	-		
P14	GND	-		
P5	GND	-		
R7	GND	-		
F14	VCC	-		
G11	VCC	-		
G9	VCC	-		
H7	VCC	-		
L7	VCC	-		
M9	VCC	-		
H6	VCCIO7	7		
J7	VCCIO7	7		
M7	VCCIO6	6		
K7	VCCIO6	6		
M8	VCCIO5	5		
R9	VCCIO5	5		
M12	VCCIO4	4		
M11	VCCIO4	4		
L12	VCCIO3	3		
K12	VCCIO3	3		
J12	VCCIO2	2		
H12	VCCIO2	2		
G12	VCCIO1	1		
G10	VCCIO1	1		

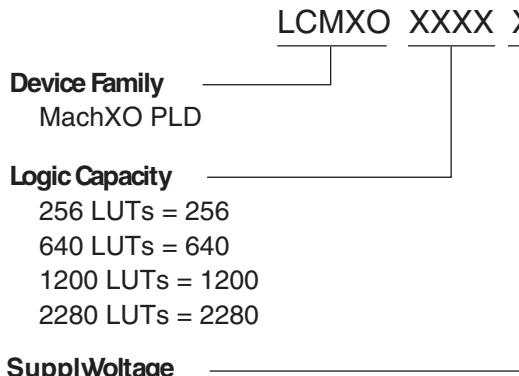


# MachXO Family Data Sheet Ordering Information

June 2013

Data Sheet DS1002

## **Part Number Description**



Note: Parts dual marked as described

ES = Engineering Sample  
Blank = Production Device

Grade

C = Commercial  
I = Industrial

## Package

T100 = 100-pin TQFP  
T144 = 144-pin TQFP  
M100 = 100-ball csBGA  
M132 = 132-ball csBGA  
B256 = 256-ball caBGA  
FT256 = 256-ball ftBGA  
FT324 = 324-ball ftBGA

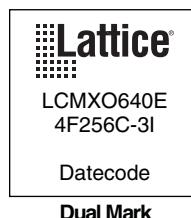
TN100 = 100-pin Lead-Free TQFP  
TN144 = 144-pin Lead-Free TQFP  
MN100 = 100-ball Lead-Free csBGA  
MN132 = 132-ball Lead-Free csBGA  
BN256 = 256-ball Lead-Free caBGA  
FTN256 = 256-ball Lead-Free ftBGA  
FTN324 = 324-ball Lead-Free ftBGA

## Speed

3 = Slowest  
4  
5 = Fastest

## **Ordering Information**

Note: MachXO devices are dual marked except the slowest commercial speed grade device.  
For example the commercial speed grade LCMXO640E-4F256C is also marked with industrial grade -3I grade.  
The slowest commercial speed grade does not have industrial markings.  
The markings appears as follows:





# MachXO Family Data Sheet

## Revision History

June 2013

Data Sheet DS1002

### Revision History

Date	Version	Section	Change Summary
February 2005	01.0	—	Initial release.
October 2005	01.1	Introduction	Distributed RAM information in family table updated. Added footnote 1 - fpBGA packaging to the family selection guide.
		Architecture	sysIO Buffer section updated.
			Hot Socketing section updated.
			Sleep Mode section updated.
			SLEEP Pin Characteristics section updated.
			Oscillator section updated.
		DC and Switching Characteristics	Security section updated.
			Recommended Operating Conditions table updated.
			DC Electrical Characteristics table updated.
			Supply Current (Sleep Mode) table added with LCMXO256/640 data.
			Supply Current (Standby) table updated with LCMXO256/640 data.
			Initialization Supply Current table updated with LCMXO256/640 data.
			Programming and Erase Flash Supply Current table updated with LCMXO256/640 data.
			Register-to-Register Performance table updated (rev. A 0.16).
			External Switching Characteristics table updated (rev. A 0.16).
			Internal Timing Parameter table updated (rev. A 0.16).
			Family Timing Adders updated (rev. A 0.16).
			sysCLOCK Timingupdated (rev. A 0.16).
			MachXO "C" Sleep Mode Timing updated (A 0.16).
		Pinout Information	JTAG Port Timing Specification updated (rev. A 0.16).
			SLEEPIN description updated.
			Pin Information Summary updated.
			Power Supply and NC Connection table has been updated.
		Ordering Information	Logic Signal Connection section has been updated to include all devices/packages.
			Part Number Description section has been updated.
			Ordering Part Number section has been updated (added LCMXO256C/ LCMXO640C "4W").
		Supplemental Information	MachXO Density Migration Technical Note (TN1097) added.
November 2005	01.2	Pinout Information	Added "Power Supply and NC Connections" summary information for LCMXO1200 and LCMXO2280 in 100 TQFP package.
December 2005	01.3	DC and Switching Characteristics	Supply Current (Standby) table updated with LCMXO1200/2280 data.
		Ordering Information	Ordering Part Number section updated (added LCMXO2280C "4W").
April 2006	02.0	Introduction	Introduction paragraphs updated.
		Architecture	Architecture Overview paragraphs updated.

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